

CD4094B Types

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ\text{C}$, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	VDD (V)	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For T_A =Full Package-Temperature Range)		3	18	V
Data Setup Time, t_S	5 10 15	125 55 35	— — —	ns
Clock Pulse Width, t_W	5 10 15	200 100 83	— — —	ns
Clock Input Frequency, f_{CL}	5 10 15	dc	1.25 2.5 3	MHz
Clock Input Rise or Fall time, t_r, t_f , t_{rCL} , t_{fCL} .*	5 10 15	—	15 5 5	μs
Strobe Pulse Width, t_W	5 10 15	200 80 70	— — —	ns

*If more than one unit is cascaded t_{rCL} (for Q_S only) should be made less than or equal to the sum of the fixed propagation delay at 50 pF and the transition time of the output driving stage for the estimated capacitive load.

TRUTH TABLE

CL Δ	Output Enable	Strobe	Data	Parallel Outputs		Serial Outputs	
				Q1	Q2	Q3*	Q4*
	0	X	X	OC	OC	Q7	NC
	0	X	X	OC	OC	NC	Q7
	1	0	X	NC	NC	Q7	NC
	1	1	0	0	0	Q1-1	Q7
	1	1	1	1	1	Q1-1	Q7
	1	1	1	NC	NC	NC	Q7

Δ = Level Change
X = Don't Care
NC = No Change
OC = Open Circuit

Logic 1 = High
Logic 0 = Low

* At the positive clock edge information in the 7th shift register stage is transferred to the 8th register stage and the Q_S output.

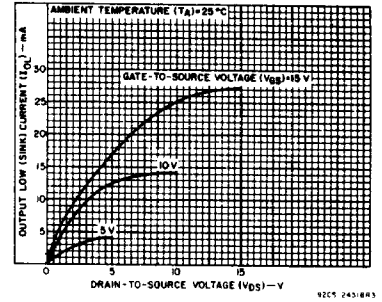


Fig. 4 - Typical output low (sink) current characteristics.

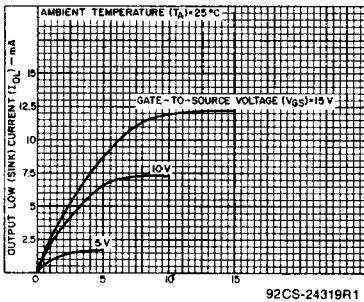


Fig. 5 - Minimum output low (sink) current characteristics.

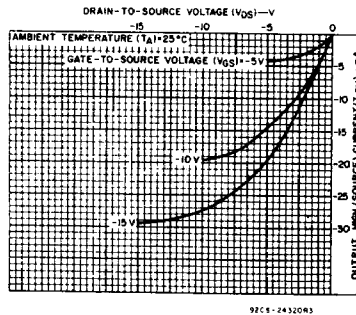


Fig. 6 - Typical output high (source) current characteristics.

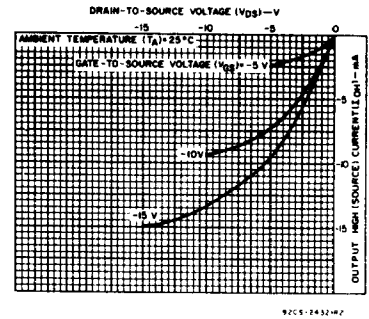


Fig. 7 - Minimum output high (source) current characteristics.

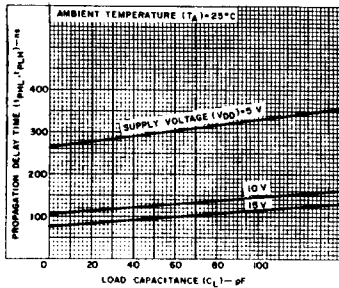


Fig. 8 - Clock-to-serial output Q_S propagation delay vs C_L .

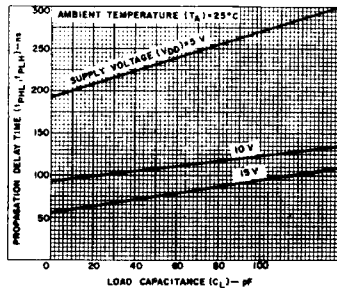


Fig. 9 - Clock-to-serial output Q'_S propagation delay vs C_L .

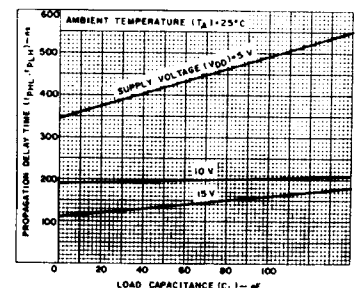


Fig. 10 - Clock-to-parallel output propagation delay vs C_L .

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	Values at -55, +25, +125 Apply to D, F, K, H Packages Values at -40, +25, +85 Apply to E Package							
				-55	-40	+85	+125	+25			
				Min.	Typ.	Max.					
Quiescent Device Current, I _{DD} Max.	-	0,5	5	5	5	150	150	-	0,04	5	μA
	-	0,10	10	10	10	300	300	-	0,04	10	
	-	0,15	15	20	20	600	600	-	0,04	20	
	-	0,20	20	100	100	3000	3000	-	0,08	100	
Output Low (Sink) Current I _{OL} Min.	0,4	0,5	5	0,64	0,61	0,42	0,36	0,51	1	-	mA
	0,5	0,10	10	1,6	1,5	1,1	0,9	1,3	2,6	-	
	1,5	0,15	15	4,2	4	2,8	2,4	3,4	6,8	-	
Output High (Source) Current, I _{OH} Min.	4,6	0,5	5	-0,64	-0,61	-0,42	-0,36	-0,51	-1	-	mA
	2,5	0,5	5	-2	-1,8	-1,3	-1,15	-1,6	-3,2	-	
	9,5	0,10	10	-1,6	-1,5	-1,1	-0,9	-1,3	-2,6	-	
	13,5	0,15	15	-4,2	-4	-2,8	-2,4	-3,4	-6,8	-	
Output Voltage: Low-Level, V _{OL} Max.	-	0,5	5	0,05			-	0	0,05	-	V
	-	0,10	10	0,05			-	0	0,05	-	
	-	0,15	15	0,05			-	0	0,05	-	
Output Voltage: High-Level, V _{OH} Min.	-	0,5	5	4,95			4,95	5	-	-	V
	-	0,10	10	9,95			9,95	10	-	-	
	-	0,15	15	14,95			14,95	15	-	-	
Input Low Voltage, V _{IL} Max.	0,5, 4,5	-	5	1,5			-	-	1,5	-	V
	1,9	-	10	3			-	-	3	-	
	1,5, 13,5	-	15	4			-	-	4	-	
Input High Voltage, V _{IH} Min.	0,5, 4,5	-	5	3,5			3,5	-	-	-	V
	1,9	-	10	7			7	-	-	-	
	1,5, 13,5	-	15	11			11	-	-	-	
Input Current I _{IJ} Max.	-	0,18	18	±0,1	±0,1	±1	±1	-	±10 ⁻⁵	±0,1	μA
3-State Output Leakage Current I _{OUT} Max.	0,18	0,18	18	±0,4	±0,4	±12	±12	-	±10 ⁻⁴	±0,4	μA

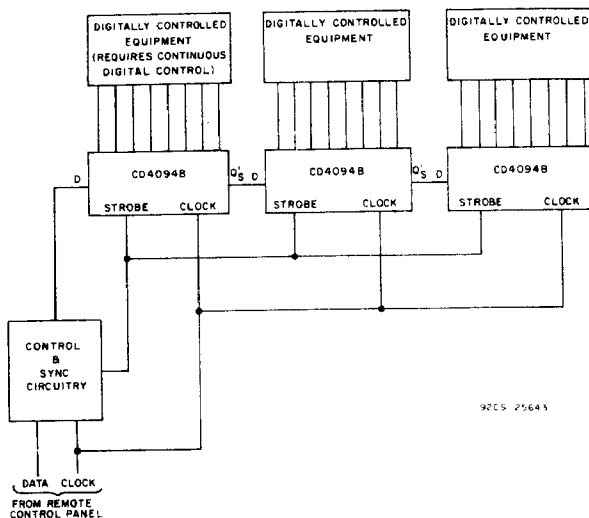


Fig. 14 - Remote control holding register.

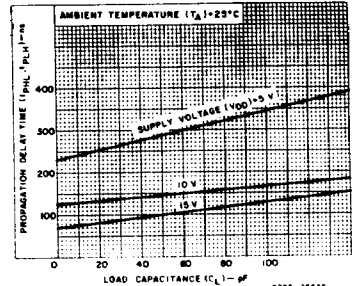


Fig. 11 - Strobe-to-parallel output propagation delay vs. C_L.

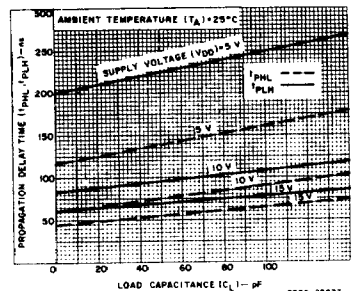


Fig. 12 - Output enable-to-parallel output propagation delay vs. C_L.

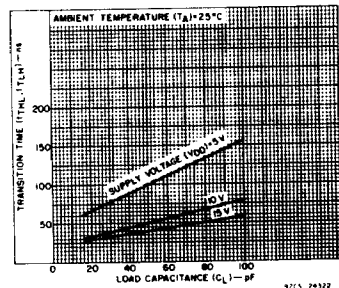


Fig. 13 - Typical transition time vs. load capacitance.

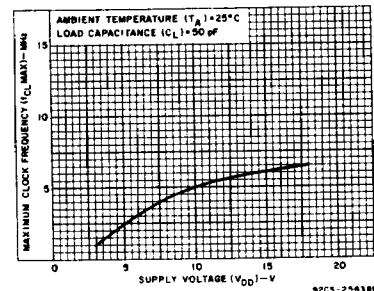


Fig. 15 - Typical maximum-clock-frequency vs. supply voltage.

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DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A=25^\circ\text{C}$; Input $t_r, t_f = 20\text{ ns}$, $C_L = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	VDD (V)	LIMITS			UNITS
		MIN.	TYP.	MAX.	
Propagation Delay Time, t_{PHL}, t_{PLH}	5	—	300	600	ns
Clock to Serial Output Q_S	10	—	125	250	
	15	—	95	190	
Clock to Serial Output Q_S^*	5	—	230	460	ns
	10	—	110	220	
	15	—	75	150	
Clock to Parallel Output	5	—	420	840	ns
	10	—	195	390	
	15	—	135	270	
Strobe to Parallel Output	5	—	290	580	ns
	10	—	145	290	
	15	—	100	200	
Output Enable to Parallel Output: t_{PHZ}, t_{PZH}	5	—	140	280	ns
	10	—	60	120	
	15	—	45	90	
t_{PLZ}, t_{PZL}	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Minimum Strobe Pulse Width, t_W	5	—	100	200	ns
	10	—	40	80	
	15	—	35	70	
Minimum Clock Pulse Width, t_W	5	—	100	200	ns
	10	—	50	100	
	15	—	40	83	
Minimum Data Setup Time, t_S	5	—	60	125	ns
	10	—	30	55	
	15	—	20	35	
Transition Time; t_{THL}, t_{TLH}	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Maximum Clock Input Rise or Fall Time, $t_r, t_f, t_{rCL}, t_{fCL}$	5	15	—	—	μs
	10	5	—	—	
	15	5	—	—	
Maximum Clock Input Frequency, f_{CL}	5	1.25	2.5	—	MHz
	10	2.5	5	—	
	15	3	6	—	
Input Capacitance C_{IN} (Any Input)	—	—	5	7.5	pF

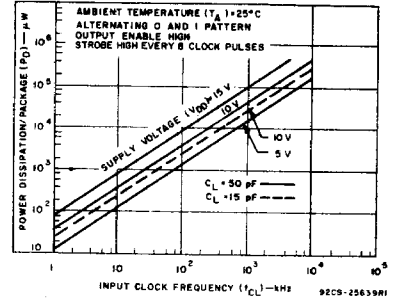


Fig. 16 — Dynamic power dissipation vs input clock frequency.

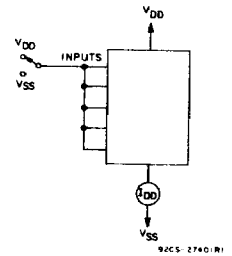


Fig. 17 — Quiescent device current test circuit.

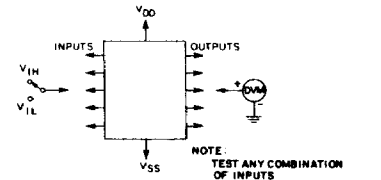


Fig. 18 — Input voltage test circuit.

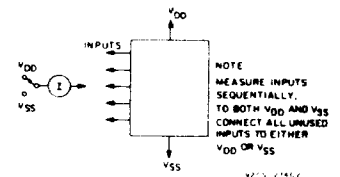
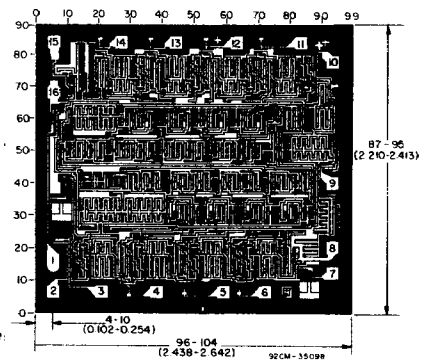


Fig. 19 — Input current test circuit.

The photographs and dimensions of each CMOS chip represent a chip when it is part of the wafer. When the wafer is separated into individual chips, the angle of cleavage may vary with respect to the chip face for different chips. The actual dimensions of the isolated chip, therefore, may differ slightly from the nominal dimensions shown. The user should consider a tolerance of ± 3 mils to ± 16 mils applicable to the nominal dimensions shown.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).



Dimensions and Pad Layout for CD4094B Chip.